An initiative of the European Union

EUCLUSTERS MATCHMAKING EVENTS

PARTICIPANTS BOOKLET

10 - 12 June 2024

EU-Taiwan

#ECCPMatchmaking

EUROPEAN CLUSTER COLLABORATION PLATFORM

European Commission

enterprise europe network
Business Support on Your Doorstep

經濟部國際貿易署
International Trade Administration

TAITRA

EU-TAIWAN MED MATCHMAKING EVENT

Background

The European Commission (EC) will organise the EU – Taiwan Matchmaking Event in the context of **Taiwan Expo 2024 in Europe** which will be held on 10-12 June 2024.

The **EU – Taiwan Matchmaking Event** itself will take place on-site in Berlin, Germany on 10-12 June 2024 with a delegation of about 80 companies and trade organisations from Taiwan.

The event will be jointly organised by the European Commission through the European Cluster Collaboration Platform (ECCP), in collaboration with the Taiwan External Trade Development Council (TAITRA), European Enterprise Network (EEN).

The **EU – Taiwan Matchmaking Event** will bring together cluster organisations and SMEs from the European Union (EU), non-EU countries participating in the Single Market Programme/COSME Strand, and Taiwan. It will provide participants an excellent chance to promote Cluster to Cluster (C2C), Cluster to Business (C2B), and Business to Business (B2B) collaborations. The event will be held on-site at Taiwan Expo in Europe, in Berlin, Germany.

OVERALL AGENDA OF THE BUSINESS MISSION BY DAYS

10 JUNE 2024

<table>
<tr><th>Time</th><th colspan="3">Programme</th></tr>
<tr><td>09:45-10:00</td><td colspan="3">Registration (EU Delegation)
Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin
Meeting point: main entrance of the building</td></tr>
<tr><td>10:30-11:30</td><td colspan="3">TAIWAN EXPO Opening Ceremony
Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin</td></tr>
<tr><td>11:30-12:00</td><td colspan="3">TAIWAN EXPO Guided Tour
Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin</td></tr>
<tr><td>11:30-13:30</td><td colspan="3">Welcoming Reception
Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin</td></tr>
<tr><td colspan="2">Semiconductor Forum
Location: Hotel De Rome</td><td colspan="2">EU – Taiwan Excellence Tech Show, EU-Taiwan Business Cooperation’s Seminar, organised by ECCP & EEN
Location: Main Expo Stage and Taiwan Excellence Pavilion</td></tr>
<tr><td>13:00 – 18:00</td><td>13:00 – 13:30
Registration & Networking
Opening remarks
Photo Session

14:00 – 14:15
Topic: TBD
Mr. Gunnar C. Thomas, General Councel, EMEA, TSMC

14:15 – 14:30
Topic: TBD
Dr. Christian Kotzsch, President, ESMC

14:30 – 14:45
Advancing the Semiconductor Ecosystem. Tackling the Industry’s Biggest Challenges through Closer Collaboration
Dr. Suresh Rajarman, Executive Vice President and Head of Thin Film Business Unit, Merck Electronics

14:45 – 15:15</td><td>14:00 – 18:00</td><td>14:00 – 16:00
Taiwan Excellence Tech Show Including performance, brand presentation, influencer interactive activity, lucky draw and onsite mini game, media interviews, happy hour)

16:00 -17:30
EU-Taiwan Business Cooperation’s Seminar, organised by ECCP & EEN

16:00 -16:45
• Pitching session – an opportunity EU & Taiwanese organisation to present their companies and offerings.
- CASTRA, Bulgaria
- Iconic Cluster, Romania
- OptecBB, Germany</td></tr>
</table>

	Session II: Taiwan-EU Collaboration in Automotive or AI Semiconductors 14:45 – 15:00 Automotive/AI Semiconductor Cooperation between EU and Taiwanese Industries *Mr. Weizhi Yu, Vice President of Automotive Product Marketing, MediaTek* 15:15 – 15:00 Semiconductors at the Heart of Decarbonization and Digitalization *Dr. Thomas Schafbauer, Executive Vice President and COO of the Connected Secure Systems Division, Infineon* **15:15 – 15:30 BREAK** **15:30 – 16:00** **Session III: Semiconductor Talent Incubation and Tech Innovation** 15:30 – 15:45 Semiconductor Sustainability and Talent Development *Mr. Terry Tsao, Global Chiev marketing Officer and President of Taiwan, SEMI* 15:45 – 16:00 Semiconductor Talent Incubation and Tech Innovation *Prof. Dr.-Ing. Albert Hauberg, Executive Director, Fraunhofer Institute for Integrated Circuits IIS* **16:00 – 16:50** **Panel Discussion: Semiconductors Driving a Sustainable Future** *Moderator: Mr. Terry Tsao, Global Chief marketing Officer and President of Taiwan, SEMI* - Dr. Yee-Wei Huang, Vice President & Spokesman, Realtek Semiconductor Group Corp; - Dr. Wolfgang Weber, CEO, ZVEI Frankfurt am Main, Germany - Dr. Torstein Thieme, CDO, DEAXO Gmbh and a Board Member, Silicon Saxony e.V.		- *Ecodomus, Italy,* - *Southwest Hungarian Engineering Cluster, Hungary* - *Finance Innovation, France* - *BioPMed, Italy* - *Lucas Wang, Assistant Vice President of Corporate Synergy Development Center* - *Larry CHEN, CEO of MIJILY CO., LTD.* - *Sammy CHIU, Vice President of Business Development of SZ JIE, Taiwan, LI ENTERPRISE CO., LTD, Taiwan* - *Deya, General Manager of UNI-PARAGON ENTERPRISE CO., LTD* - **16:45 – 17:05** • **Testimonials & Success stories of cooperation** - ***Mike Richardson,*** *Senior Project Manager Optecbb* - ***Roberto LAI,*** *Deputy International Affairs Officer of ITRI Europe Office* **17:05 – 17:45** • **Practical Aspects on EU-Taiwan Business Cooperation** • ***Dr. Jürgen Maurer***, East-Asia Correspondent, *Germany Trade and Invest (GTAI)* • ***Leonie Yang*****,** *Acting Delegate of German Business and Head of the German Trade Office Taipei)*

	16:50 – 17:10 **Q & A** **17:10 – 18:00** **Networking**		
19:30 – 21:00	**Networking Reception** *An exceptional opportunity to further expand collaboration opportunities between EU and Taiwan* **Place: Augustiner am Gendarmenmarkt** **Address:** Charlottenstraße 55, 10117 Berlin, Germany		

11 JUNE 2024

Time	Programme
10:00 -10:30	**Gathering of the EU Delegation** Location: ECCP & EEN Networking Zone, Exhibition Floor
10:30 – 12:00	**Matchmaking via B2match, online participants** Location: ECCP & EEN Networking Zone, Business zone
12-00 – 13:00	**Break, Free Time**
13:00 – 17:00	**Matchmaking, meetings with onsite participants** Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin
17:00 – 17:30	**Debriefing session: feedback harvesting for all EU Cluster participants.** Location: ECCP & EEN Networking Zone, Exhibition Floor • Performed by **Zoran Stamencic, EISMEA (European Commission)**

WEDNESDAY 12 JUNE 2024

SITE VISITS, organised in partnership with OpTecBB and Fraunhofer IZM

08:45 – 14:00*

Fraunhofer IZM

- Advanced packaging, Substrates, Process, Characterization, Technology Transfer

As part of the Fraunhofer-Gesellschaft, Fraunhofer IZM specializes in applied and industrial contract research. Fraunhofer IZM's focus is on packaging technology and the integration of multifunctional electronics into systems. The institute has a staff of more than 438 and saw a turnover of 39,6 million euros in 2022, of which 38,3 percent was earned through contract research. Fraunhofer IZM has two sites in Germany. Apart from its headquarters near Berlin Mitte, the institute is also represented in Dresden and Cottbus, strategically important centers for electronic development and manufacturing.

Of interest is the Semiconductor business unit

Business Unit - Semiconductors

Using 3D integration of components, complex, heterogeneous system-in-packages (SiP solutions) can be developed. The major advantages of 3D system architecture include:

- High miniaturization and improved form factor
- Improved performance and power efficiency thanks to the faster signal speeds and higher bandwidth via shorter and narrower signal paths
- Increased functionality due to heterogeneous integration of components, which are fabricated using various techno logies (sensor, memory, ASIC and transceiver)
- System partitioning
- Faster product implementation (also known as 'time to market')
- Fewer costs due parallelization of assembly processes

Fraunhofer IZM's services include a closed process chain – concept and process development, characterization, as well as reliability assessment and prototyping of 3D systems. All processes required throughout the chain for the realization of wafer-level packages, including through silicon via (TSV) formation, are available in our labs. 3D systems that meet the disparate target profiles demanded by various application scenarios, such as image sensors, sensor nodes, eGrains, can be realized and characterized. We work in close cooperation with tool and material suppliers to continuously improve applied technologies.

The Semiconductor business unit is supported by 4 departments:

The four Fraunhofer IZM departments promote internationally cutting-edge technology development. The departments jointly work on application areas and key development topics, ensuring the research is advanced across technologies. In key development topics, the Fraunhofer IZM researchers monitor and develop highly promising research questions, paving the way for future projects with industry.

Here, Fraunhofer IZM benefits from its close cooperation with the Technischen Universität Berlin and other scientific institutes. Fraunhofer IZM has cooperated on highly productive prliminary research with the TU Berlin since its establishment, and the close relationship between the institute and university is best illustrated by the current practice of appointing a joint IZM institute head and TU university professorship.

"Wafer Level System Integration" (WLSI)

The department "Wafer Level System Integration" (WLSI) develops advanced packaging and system integration technologies and offers customer-specific solutions for microelectronic products in the overall scope of smart system integration. Approx. 60 scientists work at two locations: Berlin and Dresden (ASSID: All Silicon System Integration Dresden). WLSI is cooperating globally with manufacturers and users of microelectronic products as well as cleanroom equipment producers and material developers from the chemical industry.

System Integration and Interconnection Technologies (SIIT),

The range of services provided by the department System Integration and Interconnection Technologies (SIIT), which has more than 100 employees, spans from consultation, to process development, right through to technical system solutions. Developing processes and materials for interconnection technologies on board, module and package levels and the integration of electrical, optical and power-electronic components and systems are at the forefront of our research.

We assist companies with application-oriented pre-competitive research, as well as the development of prototypes and small volume production. Our services include application advice, technology transfer and further qualification of personnel through practical training.

The Department Environmental and Reliability Engineering

New products and technologies have to comply with an increasing range of strict specifications, and at the same time have to be cost-efficient and environmentally friendly. The Department Environmental and Reliability Engineering supports technological developments until they reach market maturity with environmental and reliability analysis reaching from nano-characterisation level to evaluation and optimisation at the system level. Under the leadership of Dr. Nils F. Nissen, a unique combination is achieved between the established cross-sectional specialist fields of reliability and sustainability.

In view of worldwide extending markets and limited resources, every new generation of products and technologies must generate more functionality and assured reliability while consuming fewer resources. Without adequate reliability, the commercial success of an application is anyway endangered, and at the same time the environmental impact of typically production-intensive microelectronics increases furtherby premature failures or the need for replacements. Sustainable electronic technologies must therefore be reliable and have a low environmental impact.

The department of RF & Smart Sensor Systems

The department of RF & Smart Sensor Systems focuses on research and development of application-specific wireless sensor nodes, radar and proximity sensor systems as well as wireless communication and high-performance computing (HPC) modules for a wide range of application fields.

Furthermore, we perform in-depth characterization of electronic packaging technologies, and develop innova-tive designs for RF/high-speed, millimeter-wave (mmWave) and terahertz (THz) packaging.

Our R&D activities concentrate on the following areas:

- High-frequency Packaging
- Components and Modules for Communication (e.g. 5G/6G) and Computing
- Radar and Proximity Sensor Systems
- Wireless Sensor Nodes and Systems
- Micro Energy Storage
- Physical Design Tools and Software
- We collaborate closely with industry partners worldwide and provide cost-effective and innovative solutions at every level along the value chain, from materials to systems.

Start-A-Factory

Start-A-Factory is part of the Fraunhofer IZM Berlin and offers hardware developers from around the world a unique opportunity.

With the help of Fraunhofer's scientists, state-of-the-art equipment, and experts from the industry, we will take your idea from the planning stage to a first industrial grade prototype – as quickly and smoothly as possible.

Our experts help you with each step along the development cycle. No matter what it entails, the support you receive is tailor-made for your project and the goal is always paramount: turning your idea into a tangible, testable prototype.

Map with all locations

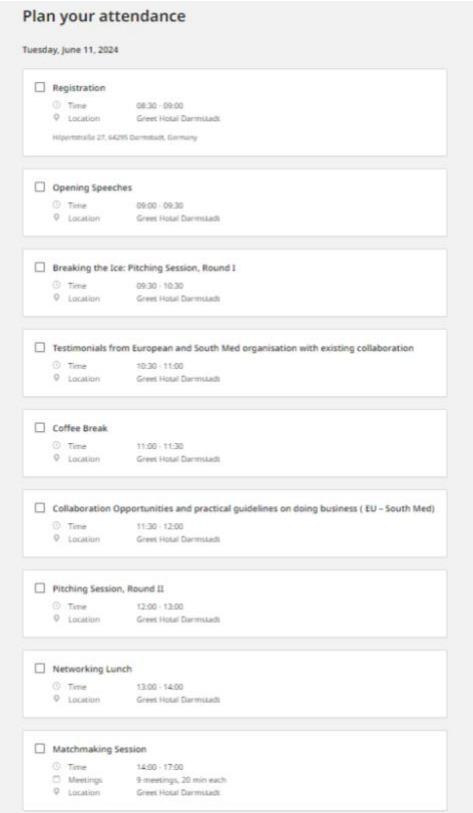
https://maps.app.goo.gl/9T5MY72p2gMTWqDL8

Photos

https://photos.app.goo.gl/dmmow1HQwJEnnBZM7

GENERAL INFORMATION AND MEETING POINTS

Register for B2Match - Plan your attendance and meetings



Register at B2Match: link HERE

- Book your meetings
- Create your matchmaking opportunities.
- Start booking meetings - Meeting requests must be accepted, otherwise they cannot be scheduled.
- Schedule your own meetings - Each matchmaking meeting will last for **20 minutes**.
    - The content of the meetings is **completely confidential**.
    - You may invite additional guests to the meeting
    - You may reschedule
    - The system is recommending meeting partners for you according to your profile
- On the day of the event, please check your meetings agenda (and download it)

MAIN VENUE: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin

Deutsche Telekom's Representative Office in Berlin-Mitte is housed in the largest and oldest surviving building from the earliest period of telecommunication in Germany. Its impressive presence has made the building something of a symbol of the identity of the

city. Built between 1863 and 1878, the building – which originally housed the country's central imperial telegraph office remains to this day the most expensive and complex postal building ever constructed in Germany. In the many decades between the time it first opened its doors and 1992, it served as the nerve center for long-distance transmissions and telecommunications in Berlin.

Today the building connects the world of interactive media with the immediate reality of futuristic technology, uniquely linking the past with the future into a unified whole. Its historic façade has been extended with a new glass construction that gives visitors an unrestricted view of its brightly-lit atrium. The effect is to create a stylish, modern atmosphere.

GENERAL TAIWAN EXPO INFORMATION

The TAIWAN EXPO 2024 in Europe focuses on the latest European Union policies, including the "European Green Deal" and "A Europe fit for the digital age", integrating local market demands and trends. The EXPO is themed around sustainability, technology, and culture, combining advanced concepts with Taiwan's excellent technological capabilities and applying them to various aspects of life, thereby creating a flagship platform for Taiwan-Europe cooperation.

The exhibition has chosen Berlin, Germany, the largest in Europe and the fourth-largest economy globally, as its venue. Germany has long maintained its leadership in industry and advanced manufacturing and is also Taiwan's largest trading partner in Europe. Berlin, the capital city, serves not only as the largest city but also as a political and cultural center and a hub of European transportation. In recent years, it has also emerged as a global gathering place for technological innovation and innovative enterprises.

The planned exhibition content includes smart living, smart transportation, smart healthcare, low-carbon environmental protection, Taiwanese cuisine, cultural creativity,

and other advantageous industries, aiming to allow more Europeans to personally experience and understand Taiwan's soft and hard power, effectively enhancing goodwill and identification towards Taiwan. Additionally, there will be a focus on Taiwan-Europe semiconductor cooperation, with the organization of a Taiwan-Europe Semiconductor Cooperation Forum during the exhibition, aimed at deepening cooperation and interaction between Taiwan and Europe in the semiconductor industry.

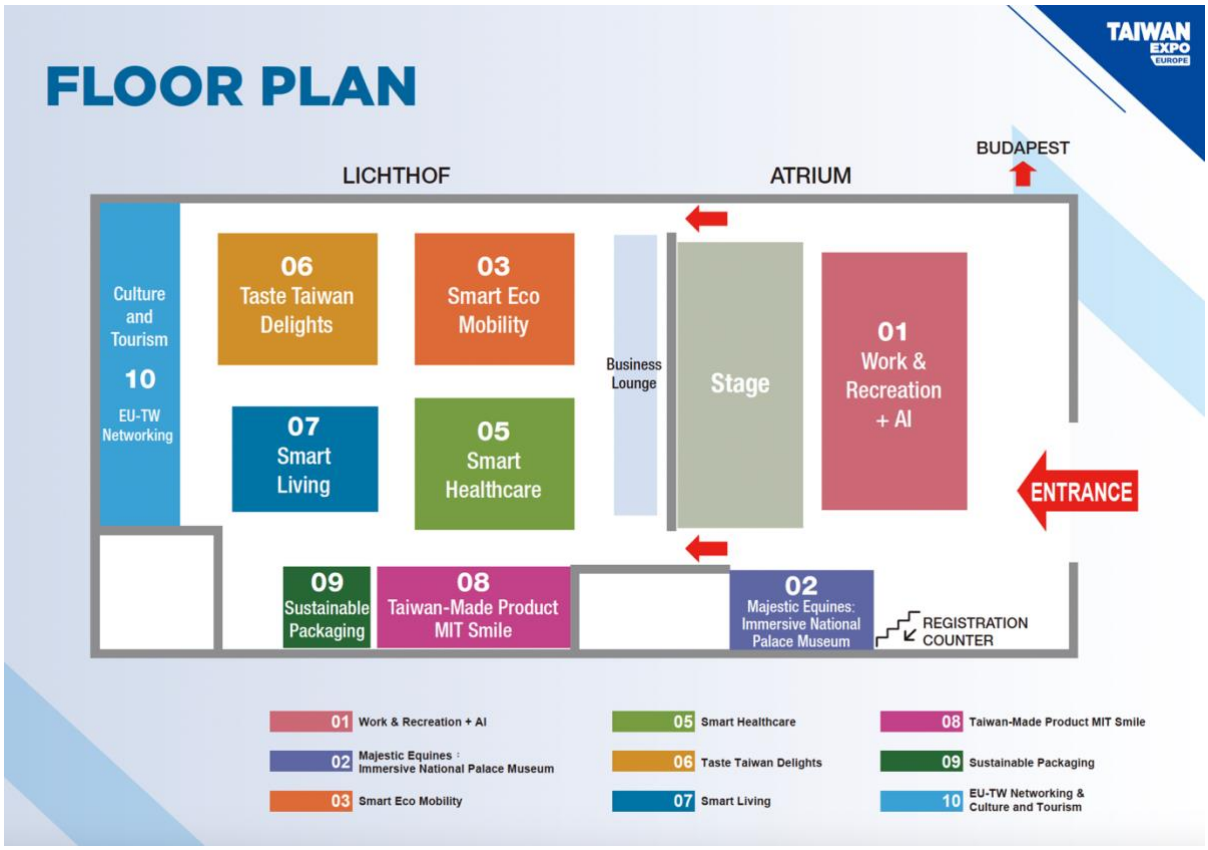
Opening Hours

10.06 10:00- 18:00 11.06 10:00- 18:00 12.06 10:00- 17:00

Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin

Official website: https://www.taiwanexpoeurope.com.tw

Floor Plan:



10 June 2024

09:45-10:00 – Registration (EU Delegation)

Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin

Meeting point: Main entrance of the building

10:30-11:30 TAIWAN EXPO Opening Ceremony

11:30-12:00 TAIWAN EXPO Guided Tour

11:30-13:30 Welcoming Reception

14:00 - EU – Taiwan Excellence Tech Show

EU-Taiwan Business Cooperation's Seminar, organised by ECCP & EEN

Location: Main Expo Stage and Taiwan Excellence Pavilion

13:00 - **Semiconductor Forum**

Location: Hotel De Rome – about 7 mins walking distance

19:30 – 21:00 Networking Dinner at Augustiner am Gendarmenmarkt

Address: Charlottenstraße 55, 10117 Berlin, Germany

11 June 2024, Matchmaking Event

10:00 – 10:30 – Gathering of the EU Delegation

Location: ECCP & EEN Networking Zone, Exhibition Floor at Deutsche Telekom AG Hauptstadtrepräsentanz

10:30 – 12:00 Matchmaking via B2match, online participants

13:00 – 17:00 Matchmaking, meetings with onsite participants

17:00 – 17:30 Debriefing session: feedback harvesting for all EU Cluster participants.

Location: ECCP & EEN Networking Zone, Exhibition Floor

12 June 2024, Site Visits

08:45 – 14:00*

The site visits are an official part of the EU-Taiwan MED Matchmaking mission and will be held on 12 June 2024.

SITE VISITS are organised in partnership with OpTecBB and Fraunhofer IZM

Meeting point: main entrance of the building

Location: Deutsche Telekom AG Hauptstadtrepräsentanz, Franz. Str. 33a-c, 10117 Berlin

Meeting Time: 08:45 CET

After gathering, the group will jointly make their way to Fraunhofer IZM by public transport.

Map with all locations:

https://maps.app.goo.gl/9T5MY72p2gMTWqDL8

Photos

https://photos.app.goo.gl/dmmow1HQwJEnnBZM7

OTHER USEFUL INFORMATION

How to get to Deutsche Telekom AG Hauptstadtrepräsentanz

From the airport

The fastest connections from the airport to the Deutsche Telekom AG Hauptstadtrepräsentanz grounds are as follows:

1. BER Airport – Terminal 1-2 take the train to Berlin Ostbahnhof, then get off and take the bus 147 to Werderscher Markt (Berlin)
2. BER Airport – Terminal 1-2 take the train to Alexanderplatz, then walk about 1.3 km to Deutsche Telekom AG Hauptstadtrepräsentanz

From Best Western Am Spittelmarkt 3*

1. You can walk about 1.0 km – 13 min or take subway U2 from U Spittelmarkt to U Hausvogteiplatz

From Novotel Berlin Mitte 4*

1. You can walk about 1.0 km – 13 min or take the bus 147 from Fischerinsel (Berlin)

CURRENCY AND PAYMENT

The official currency of Germany is the Euro (EUR).

WEATHER

Between 10 to 14 June 2024, it is expected to be partly cloudy in Berlin. The temperature will be around 20C

LANGUAGE

You will be able to speak English and German.

TIPPING

A tip of 10% is generally expected at sit-down restaurants. It is ok not to leave a tip if you are not satisfied with the service. If this is the case, you should tell your food server why you are not leaving a tip so they may (hopefully) be aware of what went wrong and help the restaurant do better next time.

After event Debriefing survey (will be sent via EU Survey)

All fields are mandatory.

1. Organisation Profile

Cluster Organization	
Country:	
Contact Person:	
Position/Title:	
E-mail Contact Person:	
Phone:	
Gender:	Male ☐ Female ☐
Is it the first time that your organisation attends a Matchmaking Event organised by ECCP?	*Yes* ☐ No ☐ Not sure ☐

2. Impact of the Event

Indicator	**Number**
Total number of total **formal** meetings conducted (online or ad hoc)	
Total number of total **informal** meetings conducted (i.e. networking during breaks, lunches, etc.)	
Formal meetings breakout	
Please indicate how many of your **formal** meetings were conducted with non-European organisations (online or ad hoc)	
Please indicate how many of your **formal** meetings were conducted with European organisations (Clusters and SME's)	
Informal meetings breakout	
Please indicate how many of your **informal** meetings were conducted with non-European organisations (online or ad hoc)	
Please indicate how many of your **informal** meetings were conducted with European organisations (Clusters and SME's)	
How many cooperation cases do you expected to be initiated following this event?	

2.1 Cooperation cases details

Based on the number provided in last question above, **it is mandatory to present in detail at least 2 cooperation cases**:

Cooperation initiated with the following organisation:	
☐ European Cluster ☐ European firm ☐ Non-European Cluster/Organisation ☐ Non-European firm	
Organisation Name (or main activity if confidential):	
Organisation Country:	
Organisation Sector:	
Organisation website (if available)	
Type of collaboration:	
☐ Research & Development ☐ Technology transfer ☐ Exports ☐ Imports ☐ Soft Landing services ☐ Staff Exchange ☐ Academic ☐ FDIs: Inward/outward ☐ Other (specify):	
Please briefly describe the collaboration purpose / activity that has been considered, agreed upon, launched, or established, as well as the precise actions/implementation stages that you intend to take or have taken (quality examples provided below):	

Example 1:

During our meeting with (partner name) we discussed and expressed mutual interest in joint RTD and demonstration activities. During follow-up telco we extended this discussion to more specific issues. Next steps were set as follows:

1. X and Y counterparts will scan possible calls suitable for X to join EU joint proposal preparation for demo sites, technology development and transfer.
2. Certification services provided by X for EU modules to enter Morocco as X is soon to be accredited laboratory for this topic. The cluster expressed their willingness to support X with available knowledge on accreditation of the PV testing lab as well as certification activities.
3. Under discussion still how we can transfer “Building Integrated Photovoltaics" installation best practices to Morocco.
4. Joint manufacturing facilities can be also topic for further discussions and joint collaboration.

Example 2:

The collaboration purpose is as follows: to find partners in our network in order to take advantage of Y world class and unique timing offerings. This means mutually collaborative import-export because they have a key component that is useful for optical communications.

For research and development their expertise with creating custom quartz crystals and patented process for scoring sections of quartz in order to create ultra precise timing oscillators is of great interest to our members and there are opportunities via Horizon funding for collaborative research that can help both entities.

We have held two meetings after the Taiwan event and have the third one scheduled.

3. Relevance of the event towards individual objectives

Testimonial
Please provide a few statements describing the outcome or results you have achieved or expected to accomplish because of this event (your testimonial may be included in ECCP related publications and allowed access on the ECCP).

Indicator	Score (0 – 5)
Vision and knowledge of new markets and technology trends	
Knowledge of geographical market entry barriers for cluster organisations / members	
Signature of cooperation agreements between companies and/or laboratories within participating Singaporean organisations	
Development of new business activities	
Increased international visibility and market penetration: facilitate search for strategic alliances/partners	
Accessing new research and innovation competences and developing concrete projects	

4. Overall Quality of the Event

Indicator	
Did the event meet your expectations?	*Yes* ☐ No ☐
Did you consider the presentations suitable to the event?	*Yes* ☐ No ☐
How was the quality of the overall event?	Rate from 1 to 5
How was the quality of the preparation webinar?	Rate from 1 to 5
How was the quality of the information provided before the event?	Rate from 1 to 5
How would you rate the quality of the matchmaking sessions?	Rate from 1 to 5
How would you rate the quality of the facilities?	Rate from 1 to 5

Participation of Singaporean clusters and cluster-like organisations, and SMEs in the event for establishing further partnerships / contact	Rate from 1 to 5
Is 20 minutes per meeting a proper time for you in these kinds of events?	*Yes* ☐ No ☐
Please submit your ideas for improving future cluster matching events:	
What countries are you interested in partnering with (both in the EU and globally)? Would organizing a matchmaking event connected to these nations be beneficial to you (either in the EU or in the individual country)?	

Members of the EU Delegation (ECCP Group)

Participation status: In Person

Update: 7 June 2024

Cluster Organisation:	Country	www-Address:	Sector(s) of Activity (in short):	ECCP profile
CASTRA	Bulgaria	www.castra.org	AI/IoT/Advanced Manufacturing	https://profile.clustercollaboration.eu/profile/cluster-organisation/96b136f3-a67c-4b6c-8a9c-fe7d4526ed50
Iconic Cluster	Romania	https://iconic.ro/	ICT/Semiconductors and Digital Industries	https://profile.clustercollaboration.eu/profile/cluster-organisation/aa28497f-0c40-478c-9cab-bcfa33f385f7
Ecodomus Cluster	Italy	https://www.distrettoecodomus.com/	Green/Circular Economy/Renewable Energy/Sustainability	https://profile.clustercollaboration.eu/profile/cluster-organisation/1ce8d83b-25a9-4a3c-bcb8-94fda1bcc867
Southwest Hungarian Engineering Cluster	Hungary	www.ddgk.hu	AI/IoT/Advanced Manufacturing	https://profile.clustercollaboration.eu/profile/cluster-organisation/6391ea9f-4449-468a-b930-acfde5c312de
FINANCE INNOVATION	France	www.finance-innovation.org	ICT/Semiconductors and Digital Industries	https://clustercollaboration.eu/users/gisela-sanchez?check_logged_in=1
Optecbb	Germany	https://optecbb.de/	ICT/Semiconductors and Digital Industries	https://profile.clustercollaboration.eu/profile/cluster-organisation-member/25dede93-20f3-4eb5-944c-a33e742b6b96
bioPmed	Italy	https://biopmed.eu/	Smart Healthcare	https://profile.clustercollaboration.eu/profile/cluster-organisation/315886af-45d7-4334-8f9f-71e1d550cd6b